

ABSTRACT OF THE DISCLOSURE

In a single-sided paper phenolic resin copper-clad laminate composed of a phenolic resin impregnated paper base having copper foils laminated on and resists applied on the face side thereof, resists formed of the same material as the resists on the face side are applied also on the reverse side of the phenolic resin impregnated paper base, so that the face side and the reverse side match approximately with each other in thermal expansibility. The single-sided paper phenolic resin copper-clad laminate warps only slightly even when the peak temperature is raised to a degree suitable for lead-free solder in the reflow process for mounting electronic components.

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